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Attorney Docket No.: COOL-01901

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Daniel J. Lenehan et al.

Serial No.: 10/731,674

Filed: December 8, 2003

For: **PUMP AND FAN CONTROL
CONCEPTS IN A COOLING
SYSTEM**

} Group Art Unit: 3753

} Examiner:

TRANSMITTAL LETTER

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

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You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #58124); (EFS ID #58126); and (EFS ID #58127) filed on March 30, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
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CERTIFICATE OF MAILING (37 CFR§ 1.8(a))

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #58124); (EFS ID #58126); and (EFS ID #58127). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
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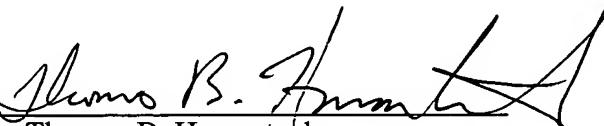
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Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3-30-04

By: 
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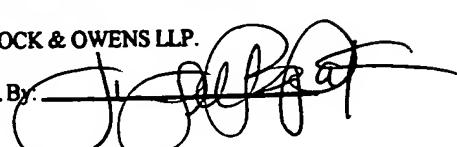
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary) (37 CFR § 1.98(b))			Applicants: Daniel J. Lenehan et al.					
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C I P E P A T E N T & T R A D E M A R K S O F F I C E A P R 0 1 2004 C 105 FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS								
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AA	97212126.9	03/04/97	CN	BO1D	61/42		X	
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